WHAT IS CLAIMED IS:

1. A wafer comprising:

a substrate including a first region and a second region that do not overlap each other;

a first chip unit and a second chip unit each arranged on the substrate;

a first electrode and a second electrode each electrically connected to the first chip unit; and

a third electrode and a fourth electrode each electrically connected to the second chip unit,

wherein the first electrode and the third electrode are arranged in the first region,

the second electrode and the fourth electrode are arranged in the second region, and

the first region is independent of a region in which the first chip unit and the second chip unit are provided.

2. The wafer according to claim 1, further comprising:

a fifth electrode configured to electrically connect the first electrode and the first chip unit;

a sixth electrode configured to electrically connect the second electrode and the first chip unit;

a seventh electrode configured to electrically connect the third electrode and the second chip unit; and

an eighth electrode configured to electrically connect the fourth electrode and the second chip unit.

3. The wafer according to claim 2, wherein

the first region and the second region are included in a region of the substrate viewed from a first surface side of the substrate.

4. The wafer according to claim 3, further comprising:

a first insulating layer arranged between (i) the first electrode, the second electrode, the third electrode, and the fourth electrode and (ii) the fifth electrode, the sixth electrode, the seventh electrode, and the eighth electrode,

wherein the first insulating layer contains polyimide.

5. The wafer according to claim 2, wherein

the first region is included in a region of the substrate viewed from a first surface side of the substrate, and

the second region is included in a region of the substrate viewed from a second surface side of the substrate opposing the first surface.

6. The wafer according to claim 5, further comprising:

a second insulating layer including a first portion arranged between (i) the first electrode and the third electrode and (ii) the substrate, a second portion arranged between (iii) the second electrode and the fourth electrode and (iv) the fifth electrode, the sixth electrode, the seventh electrode, and the eighth electrode, and a third portion arranged on a side surface of the substrate and connecting the first portion and the second portion to each other,

wherein the second insulating layer contains polyimide.

7. The wafer according to claim 1, wherein

the first electrode, the second electrode, the third electrode, and the fourth electrode each contains conductive carbon, conductive rubber, or mercury.

8. The wafer according to claim 1, wherein

the first electrode, the second electrode, the third electrode, and the fourth electrode each has a plate structure, a wire structure, a ball structure, a spring structure, or a porous structure.

9. The wafer according to claim 1, wherein

the first electrode and the third electrode are for electric power supply, and

the second electrode and the fourth electrode are for signal communication.

~~10. A prober comprising:~~

~~a supporting member configured to support a wafer;~~

~~a probe card including a first electrode arranged in a first region and a second electrode arranged in a second region, the probe card being positioned opposite the supporting member with respect to the wafer supported by the supporting member;~~

~~a torque mechanism configured to bring the first electrode and the second electrode into contact with the wafer supported by the supporting member;~~

~~a pressure sensor configured to measure a pressure distribution including a first pressure in the first region and a second pressure in the second region; and~~

~~a controller,~~

~~wherein in an operation of bringing the first electrode and the second electrode into contact with the wafer supported by the supporting member, the controller is configured to drive the torque mechanism based on the pressure distribution such that the first pressure and the second pressure differ from each other.~~

~~11. The prober according to claim 10, wherein~~

~~the first region is positioned outside the second region on a contact surface between the wafer and the probe card, and~~

~~the first pressure is higher than the second pressure.~~

~~12. The prober according to claim 10, further comprising:~~

~~a first cushioning material corresponding to the first region; and~~

~~a second cushioning material corresponding to the second region, the second cushioning material differing from the first cushioning material.~~

~~13. The prober according to claim 12, wherein~~

~~the first cushioning material and the second cushioning material each has a porous structure or a spring structure.~~

~~14. The prober according to claim 12, wherein~~

~~the first cushioning material and the second cushioning material are provided in the supporting member.~~

~~15. The prober according to claim 12, wherein~~

~~the first cushioning material and the second cushioning material are provided in the probe card.~~

~~16. The prober according to claim 12, wherein~~

~~the first cushioning material and the second cushioning material are positioned opposite the supporting member with respect to the probe card.~~

~~17. The prober according to claim 12, further comprising:~~

~~a heat dissipation mechanism including a first portion provided on a region of a bottom surface of the probe card other than the first electrode and the second electrode, a second portion provided on a side of the~~

~~probe card, and a third portion provided in the probe card and connecting the first portion and the second portion to each other,~~

~~wherein at a time of bringing the first electrode and the second electrode into contact with the wafer, the first portion of the heat dissipation mechanism is configured to be in contact with the wafer.~~

~~18. A prober comprising:~~

~~a supporting member including a first electrode and configured to support a wafer while bringing the first electrode into contact with the wafer;~~

~~a probe card including a second electrode and being positioned opposite the supporting member with respect to the wafer supported by the supporting member; and~~

~~a torque mechanism configured to bring the second electrode into contact with the wafer supported by the supporting member.~~

~~19. The prober according to claim 18, wherein~~

~~the first electrode and the second electrode are pin-shaped, and~~

~~the prober further comprises:~~

~~a first insulator provided on a region of a top surface of the supporting member that excludes the first electrode; and~~

~~a second insulator provided on a region of a bottom surface of the probe card that excludes the second electrode.~~

~~20. The prober according to claim 18, wherein the first electrode has a plate structure, a clip structure, or a ball structure.~~